

**WHAT IS CLAIMED IS:**

1. A printed wiring substrate comprising:

a core substrate having a front surface and a back surface; and

an electronic component embedded via a resin in a through-hole  
extending through said core substrate between the front surface and back  
5 surface of the core substrate;

said printed wiring substrate characterized in that:

said electronic component has an electrode projecting from at least  
either an upper end or a lower end thereof; and

the resin contains an inorganic filler.

2. A printed wiring substrate comprising:

a core substrate having a front surface and a back surface; and

an electronic component embedded via a resin in a recess formed in  
said core substrate and extending from an interior of said core substrate to the  
5 front surface or back surface of the core substrate;

said printed wiring substrate characterized in that:

said electronic component has an electrode projecting from at least  
either an upper end or a lower end thereof; and

the resin contains an inorganic filler.

3. A printed wiring substrate comprising:

a core substrate having a front surface and a back surface; and

an electronic component embedded in said core substrate;

said printed wiring substrate characterized in that:

- 5        said electronic component has an electrode projecting from at least either an upper end or a lower end thereof; and

said core substrate contains an inorganic filler.

4.        The printed wiring substrate as claimed in claim 1, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

5.        The printed wiring substrate as claimed in claim 2, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

6.        The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

7.        The printed wiring substrate as claimed in claim 1, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

8. The printed wiring substrate as claimed in claim 2, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

9. The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

10. The printed wiring substrate as claimed in claim 4, wherein the inorganic filler has a particle size not greater than 25  $\mu\text{m}$ , and the electrode has a height of at least 50  $\mu\text{m}$ .

11. A method for manufacturing a printed wiring substrate  
5 comprising a core substrate having a front surface and a back surface and an electronic component embedded via a resin in a through-hole extending through the core substrate between the front surface and back surface of the core substrate or in a recess formed in the core substrate and extending from an interior of the core substrate to the front surface or the back surface, said  
10 method comprising the steps of:

inserting into the through-hole or the recess the electronic component having an electrode projecting from at least either an upper end or a lower end thereof;

embedding the electronic component in the through-hole or the recess  
15 by means of a resin containing an inorganic filler; and

polishing a surface of the resin so as to expose an end surface of the electrode.